

C0603C399D2TACTU

Aliases (C0603C399D2TAC7867) SMD Comm X8G HT150C, Ceramic, 3.9 pF, +/-0.5 pF, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.5 mm



Click here for the 3D model.

General Information		
Series	SMD Comm X8G HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	3.7 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions	
Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm

Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

Specifications	
Capacitance	3.9 pF
Capacitance	5.9 pi
Measurement Condition	1 MHz 1.0Vrms
Tolerance	+/-0.5 pF
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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